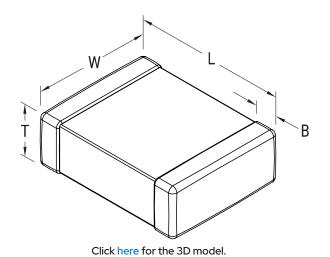


CBR08C909BAGAC

General Information

Series

CBR-SMD RF COG, Ceramic, 9 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No 12.03 mg Typical Component Weight Notes Solder Wave or Solder Reflow. Shelf Life 78 Weeks MSL 1

CBR-SMD RF COG

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

Packaging Specifications

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

Specifications	
Capacitance	9 pF
Tolerance	+/-0.1 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.172%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	580

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.